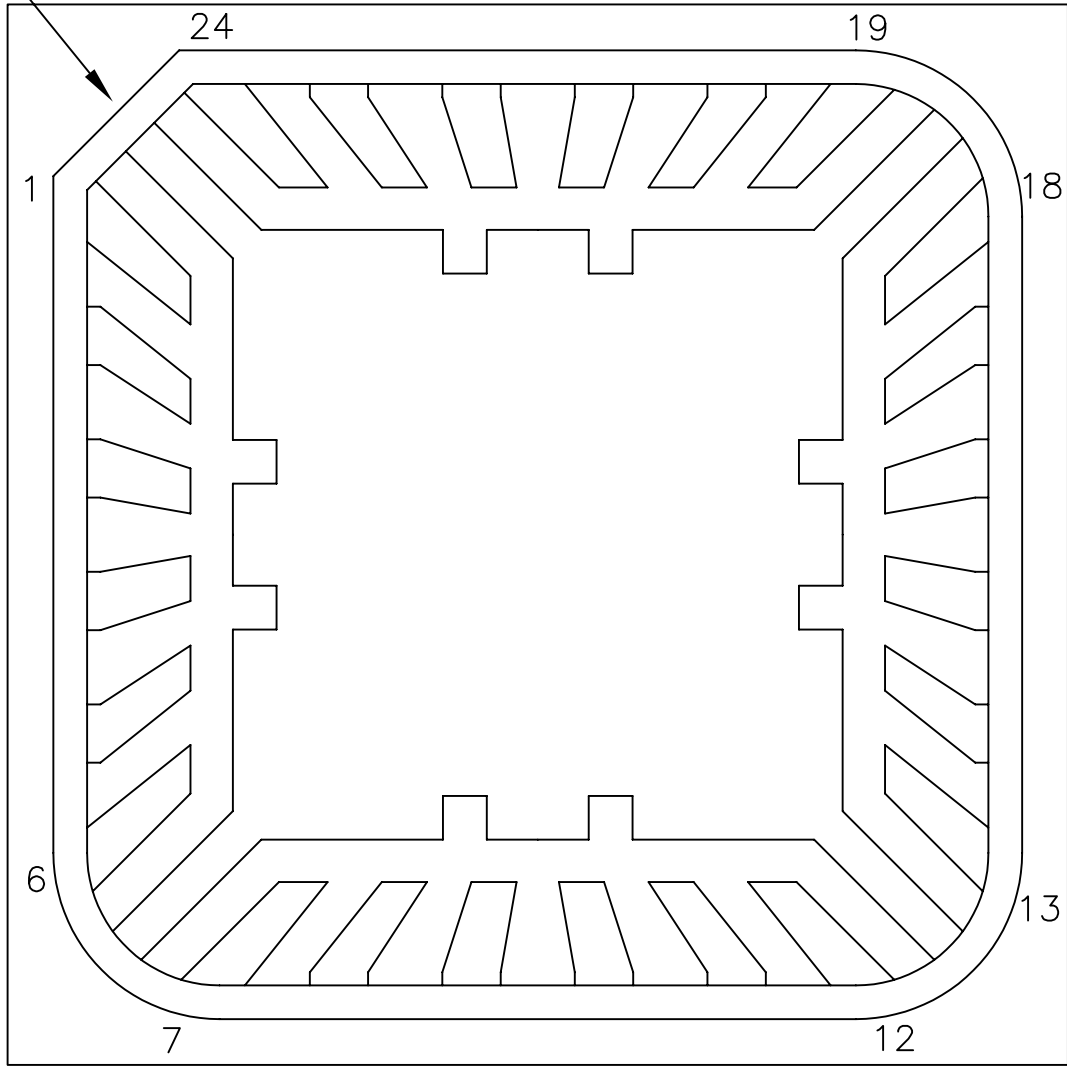


PIN #1 IDENTIFIER



DEVICE TYPE:

CUSTOMER:

WIRE TYPE/
SIZE:

DIE
SIZE:

NO. OF
WIRES:



THIRD ANGLE
PROJECTION

REVISIONS

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETER
DO NOT SCALE DRAWING

ECN NO.	DATE	DESCRIPTION	APPROVED
10489	10/25/05	INITIAL RELEASE	D.BENANDO

DRAWN
BY W. GRIFFITTS

DATE 10/25/05

PACKAGE
SIZE: 4.00mm x 4.00mm

SIZE
A

PART NO. MLP4X4-24-OP-01

REV
2

APP
BY P. FLASKERUD

DATE 10/25/05

DIE PAD
SIZE: 2.300mm x 2.300mm

SCALE 32X

CAD
FILE MLP4X4-24-OP-01-B-R2.DWG

SHEET 1 OF 1

SEMPAC, INC.

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PHONE: (408) 400-9002 FAX: (408) 400-9006

24 Lead 4mm x 4mm MLP
Open-Pak Bonding Diagram